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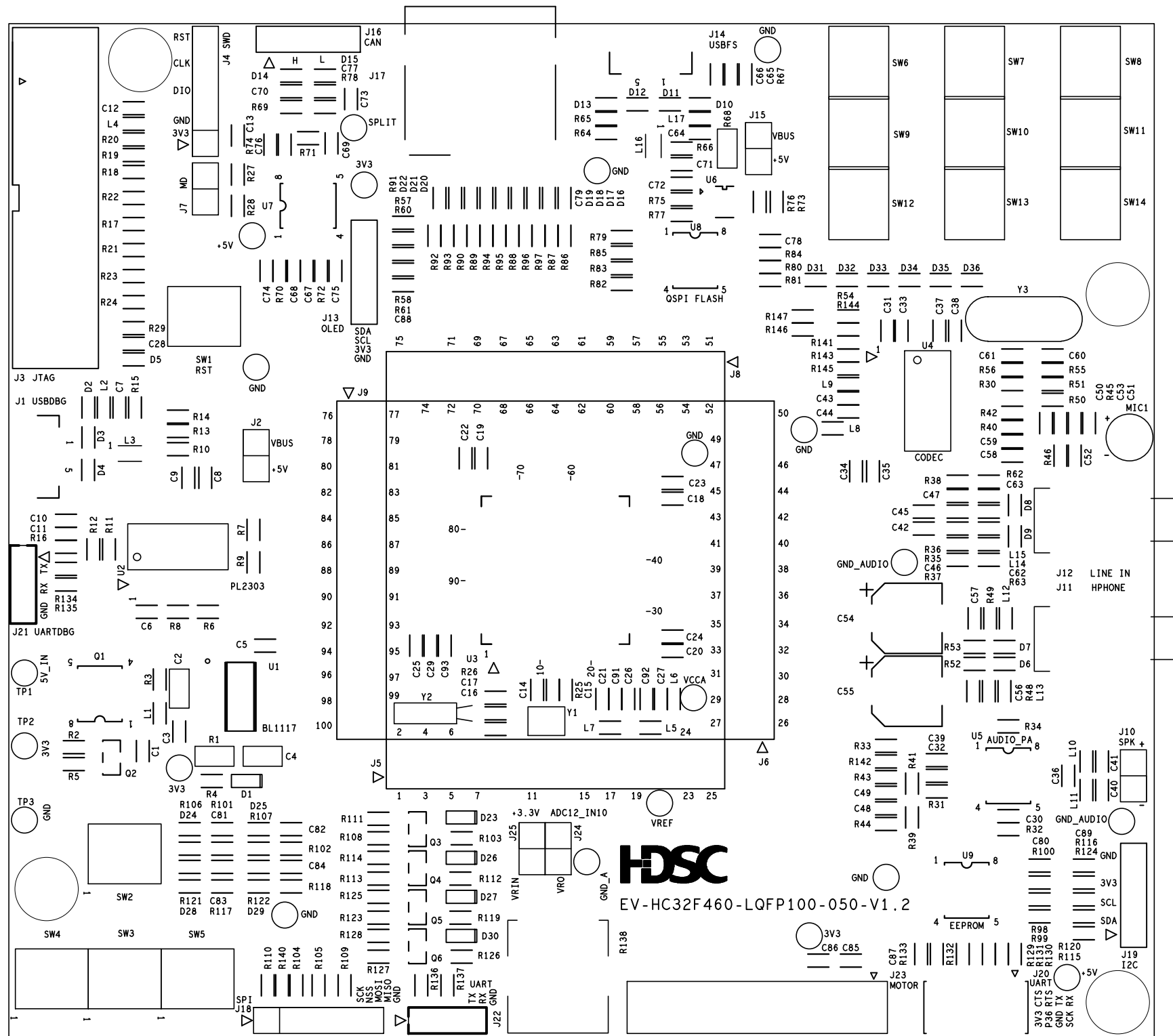
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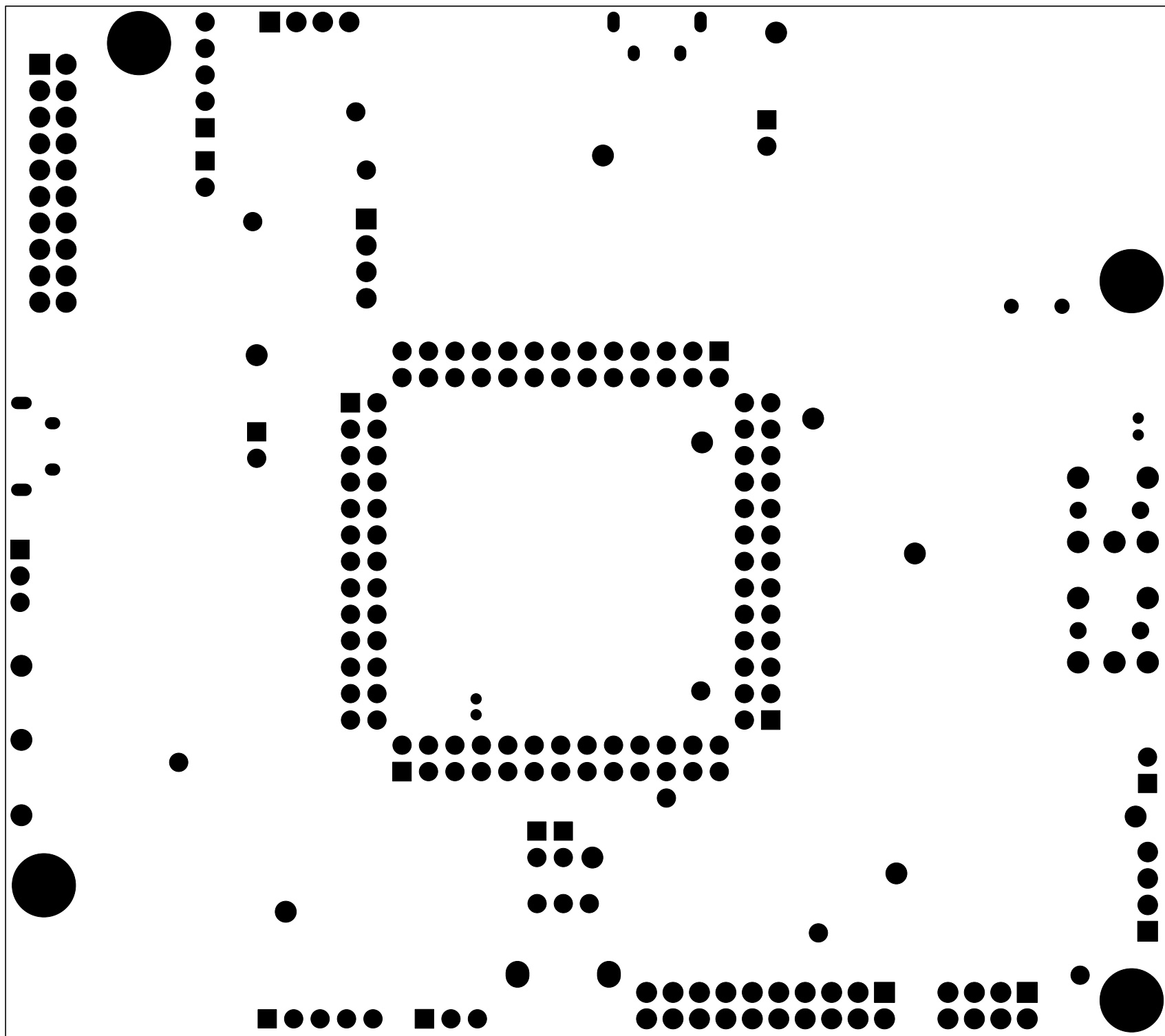
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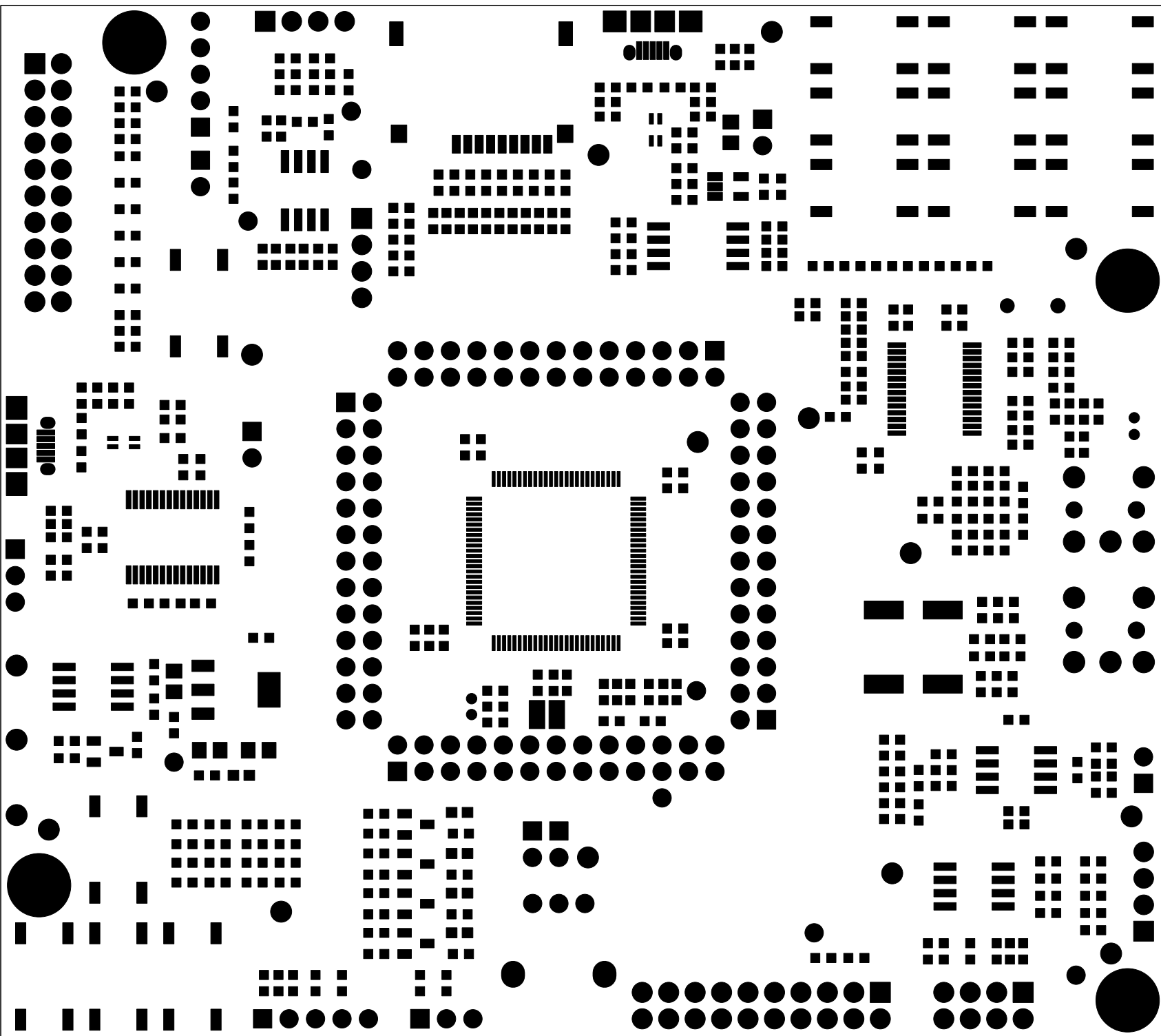
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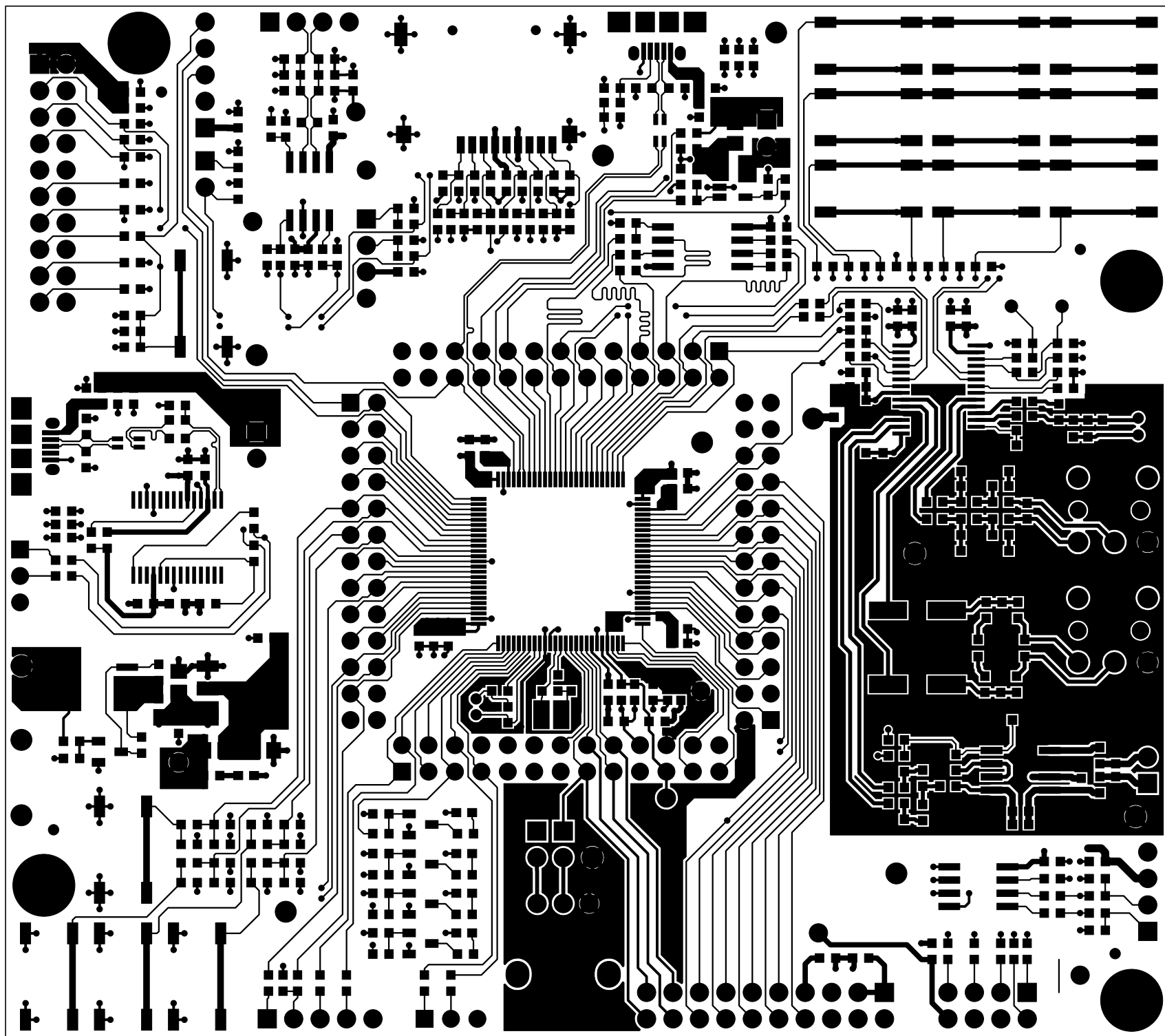
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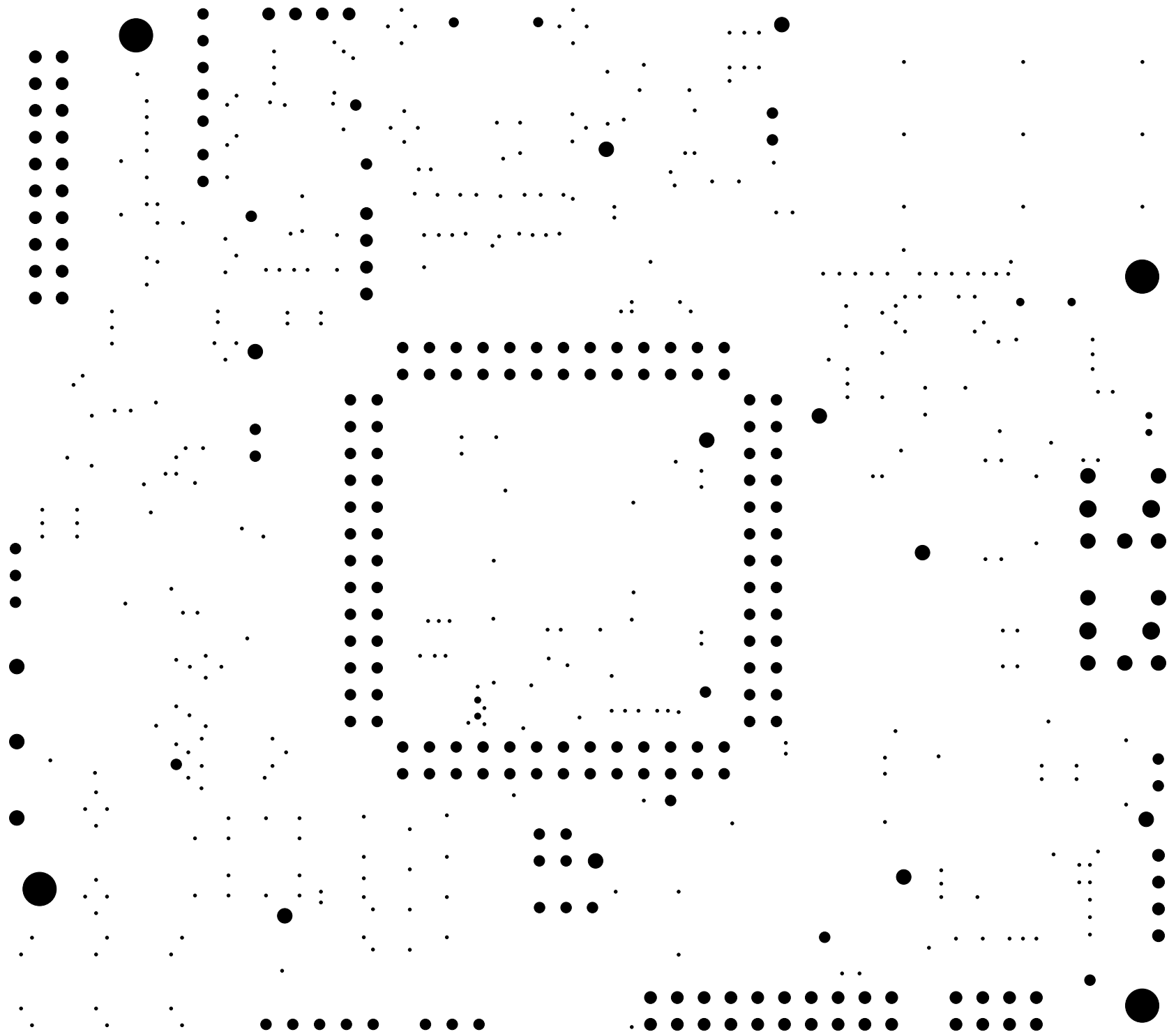
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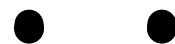


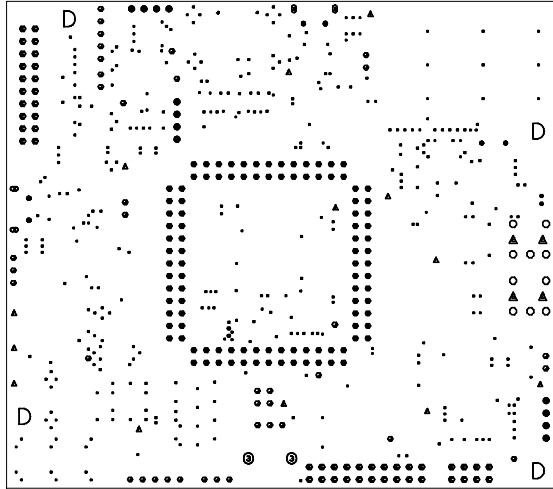




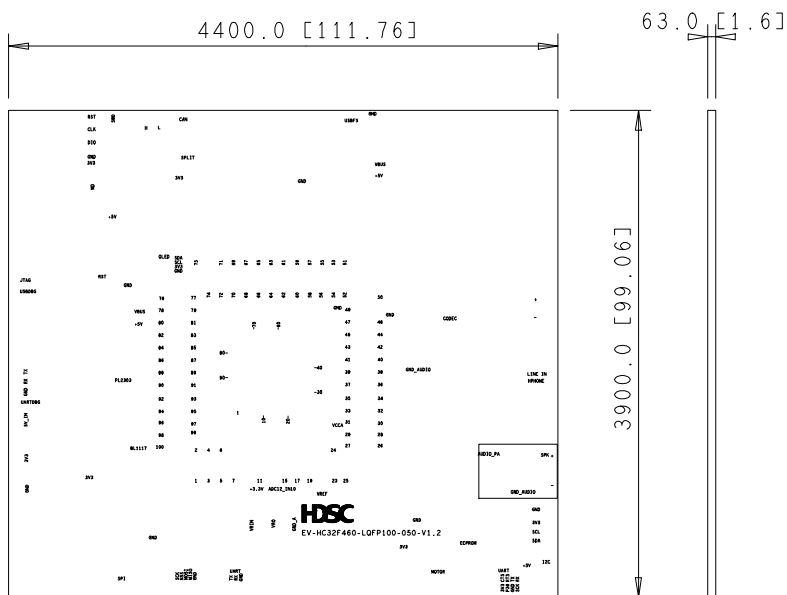








DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	12.0	+3.0/-3.0	PLATED	377
•	24.0	+3.0/-3.0	PLATED	4
•	28.35	+3.0/-3.0	PLATED	2
•	40.0	+3.0/-3.0	PLATED	39
•	40.16	+3.0/-3.0	PLATED	104
•	45.0	+3.0/-3.0	PLATED	12
•	45.67	+3.0/-3.0	PLATED	48
◦	55.0	+0.0/-0.0	PLATED	10
▲	56.0	+3.0/-3.0	PLATED	13
D	126.0	+5.0/-5.0	PLATED	4
•	35.43	+0.0/-0.0	NON-PLATED	2
▲	63.0	+5.0/-5.0	NON-PLATED	4
•	34.0x30.0	+3.0/-3.0	PLATED	2
•	34.0x30.0	+3.0/-3.0	PLATED	2
•	59.0x33.0	+3.0/-3.0	PLATED	2
•	59.0x33.0	+3.0/-3.0	PLATED	2
⊗	88.0x76.0	+3.0/-3.0	PLATED	2



LAYER STACKUP

X.SECTION	LAYER NAME	DESCRIPTION	FINISHED CU	THICKNESS
	SILKSCREEN	WHITE		
	SOLDER MASK	GREEN		0.8mil
	LAYER 1	TOP SIDE	1/3+2/3 oz	1.38mil
	PP	2313		3.5mil
	LAYER 2	GND	1/2 oz	0.69mil
	CORE			51.2mil
	LAYER 3	PWR	1/2 oz	0.69mil
	PP	2313		3.5mil
	LAYER 4	BOTTOM SIDE	1/3+2/3 oz	1.38mil
	SOLDER MASK	GREEN		0.8mil
	SILKSCREEN	WHITE		

VIA PLATING 1/3 oz min.

IMPEDANCE REQUIREMENTS

IMPEDANCE TOLERANCE IS +/- 10%

Layers	Single Ended		Differential						REF Layers
	Trace Width (Mils)	Impedance (Ohms)	Trace Width (Mils)	Trace Spacing "Airgap" (Mils)	Impedance (Ohms)	Trace Width (Mils)	Trace Spacing "Airgap" (Mils)	Impedance (Ohms)	
TOP	5.9	50	5.7	6.3	90	4.8	7.2	100	L2
L2_GND	X.XX	50	X.XX	X.XX	90	X.XX	X.XX	100	XX
L3_PWR	X.XX	50	X.XX	X.XX	90	X.XX	X.XX	100	XX
BOTTOM	5.9	50	5.7	6.3	90	4.8	7.2	100	L3

Huada Semiconductor Co.,Ltd

EV-HC32F460-LQFP100-050_V12

Rev V1.2 Date 20190111

FAB NOTES:

- ALL DEMENSION UNITS ARE IN MILS + MILLIMETERS, AND ALL DEMENSION TOLERANCE IS +/- 0.2mm.
- BOARD MATERIAL SHALL BE RoHS COMPLIANT AND LEAD FREE, BOARD MATERIAL & CONSTRUCTION TO BE UL94V0 CERTIFIED.
- PLATE ALL EXPOSED AREAS WITH Ni-Au.
- BOARD MUST BE ELECTRICALLY TESTED.